











SN754410

SLRS007C - NOVEMBER 1986-REVISED JANUARY 2015

# SN754410 Quadruple Half-H Driver

#### **Features**

- 1-A Output-Current Capability Per Driver
- Applications Include Half-H and Full-H Solenoid **Drivers and Motor Drivers**
- Designed for Positive-Supply Applications
- Wide Supply-Voltage Range of 4.5 V to 36 V
- TTL- and CMOS-Compatible High-Impedance **Diode-Clamped Inputs**
- Separate Input-Logic Supply
- Thermal Shutdown
- Internal ESD Protection
- Input Hysteresis Improves Noise Immunity
- 3-State Outputs
- Minimized Power Dissipation
- Sink/Source Interlock Circuitry Prevents Simultaneous Conduction
- No Output Glitch During Power Up or Power
- Improved Functional Replacement for the SGS L293

## **Applications**

- Stepper Motor Drivers
- DC Motor Drivers
- Latching Relay Drivers

### 3 Description

The SN754410 is a quadruple high-current half-H driver designed to provide bidirectional drive currents up to 1 A at voltages from 4.5 V to 36 V. The device is designed to drive inductive loads such as relays, solenoids, DC and bipolar stepping motors, as well as other high-current/high-voltage loads in positivesupply applications.

All inputs are compatible with TTL-and low-level CMOS logic. Each output (Y) is a complete totempole driver with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs become active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in a highimpedance state. With the proper data inputs, each pair of drivers form a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

A separate supply voltage (V<sub>CC1</sub>) is provided for the logic input circuits to minimize device power dissipation. Supply voltage V<sub>CC2</sub> is used for the output circuits.

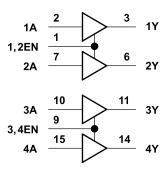
The SN754410 is designed for operation from -40°C to 85°C.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE (PIN)	BODY SIZE (NOM)
SN754410	PDIP (16)	19.80 mm × 6.35 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

# Simplified Schematic





### **Table of Contents**

1	Features 1		9.2 Functional Block Diagram	
2	Applications 1		9.3 Feature Description	
3	Description 1		9.4 Device Functional Modes	9
4	Simplified Schematic	10	Application and Implementation	10
5	Revision History		10.1 Application Information	10
6	Pin Configuration and Functions		10.2 Typical Application	10
7	Specifications	11	Power Supply Recommendations	1°
•	7.1 Absolute Maximum Ratings	12	Layout	12
	7.1 Absolute Maximum Ratings		12.1 Layout Guidelines	
	7.3 Thermal Information		12.2 Layout Example	1
	7.4 Electrical Characteristics	13	Device and Documentation Support	
	7.5 Switching Characteristics		13.1 Trademarks	
	7.6 Typical Characteristics 6		13.2 Electrostatic Discharge Caution	1
8	Parameter Measurement Information		13.3 Glossary	
9	Detailed Description 8	14	Mechanical, Packaging, and Orderable Information	
	9.1 Overview 8		IIIOIIIauoii	14

# 5 Revision History

#### Changes from Revision B (November 1995) to Revision C

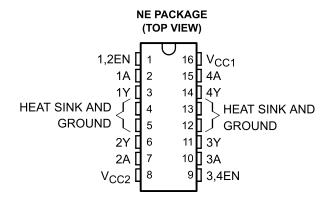
Page

- Added Applications, Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table,
  Typical Characteristics, Feature Description section, Device Functional Modes, Application and Implementation
  section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and
  Mechanical, Packaging, and Orderable Information section.
- Deleted Ordering Information table.

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# 6 Pin Configuration and Functions



#### **Pin Functions**

PIN		TYPE	DESCRIPTION
NAME	NO.	IIFE	DESCRIPTION
1,2EN	1	I	Enable driver channels 1 and 2 (active high input)
<1:4>A	2, 7, 10, 15	I	Driver inputs, non-inverting
<1:4>Y	3, 6, 11, 14	0	Driver outputs
GROUND	4, 5, 12, 13	_	Device ground and heat sink pin. Connect to circuit board ground plane with multiple solid vias
V <sub>CC2</sub>	8	_	Power VCC for drivers 4.5V to 36V
3,4EN	9	I	Enable driver channels 3 and 4 (active high input)
V <sub>CC1</sub>	16	_	5V supply for internal logic translation



### 7 Specifications

#### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)(2)

		MIN	MAX	UNIT
V <sub>CC1</sub>	Output supply voltage range	-0.5	36	V
V <sub>CC2</sub>	Output supply voltage range	-0.5	36	V
VI	Input voltage	-0.5	36	V
Vo	Output voltage range	-3	V <sub>CC2</sub> + 3	V
I <sub>P</sub>	Peak output current		±2	Α
Io	Continuous output current		±1	Α
P <sub>D</sub>	Continuous total power dissipation at (or below) 25°C free-air temperature (3)		2075	mW
T <sub>A</sub>	Operating free-air temperature range	-40	85	°C
TJ	Operating virtual junction temperature range	-40	150	°C
T <sub>stg</sub>	Storage temperature range		260	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### 7.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC1</sub>	Logic supply voltage	4.5	5.5	V
$V_{CC2}$	Output supply voltage	4.5	36	V
$V_{IH}$	High-level input voltage	2	5.5	V
V <sub>IL</sub>	Low-level input voltage	-0.3 <sup>(1)</sup>	0.8	V
$T_J$	Operating virtual junction temperature	-40	125	°C
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

<sup>(1)</sup> The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for logic voltage levels.

#### 7.3 Thermal Information

	SN754410		
	NE	UNIT	
	16 PINS		
R <sub>θJA</sub> Junc	tion-to-ambient thermal resistance	60	°C/W

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

<sup>(2)</sup> All voltage values are with respect to network GND.

<sup>(3)</sup> For operation above 25°C free-air temperature, derate linearly at the rate of 16.6 mW/°C. To avoid exceeding the design maximum virtual junction temperature, these ratings should not be exceeded. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection can be activated at power levels slightly above or below the rated dissipation.



#### 7.4 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	Т	EST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>IK</sub>	Input clamp voltage	I <sub>I</sub> = -12 m	A		-0.9	-1.5	V
		$I_{OH} = -0.5$	5 A	V <sub>CC2</sub> – 1.5	V <sub>CC2</sub> – 1.1		
$V_{OH}$	High-level output voltage	$I_{OH} = -1$ A	4	V <sub>CC2</sub> – 2			V
		$I_{OH} = -1$ A	$A, T_J = 25^{\circ}C$	V <sub>CC2</sub> - 1.8	V <sub>CC2</sub> - 1.4		
		I <sub>OL</sub> = 0.5 /	4		1	1.4	
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 1 A				2	V
			$T_J = 25^{\circ}C$		1.2	1.8	
	I <sub>OK</sub>		5 A		V <sub>CC2</sub> + 1.4	V <sub>CC2</sub> + 2	V
$V_{OKH}$	High-level output clamp voltage	I <sub>OK</sub> = 1 A			V <sub>CC2</sub> + 1.9	V <sub>CC2</sub> + 2.5	V
	Low-level output clamp voltage		I <sub>OK</sub> = 0.5 A		-1.1	-2	V
$V_{OKL}$			1		-1.3	-2.5	V
	Off-state high-impedance-state	V <sub>O</sub> = V <sub>CC</sub>	$V_O = V_{CC2}$			500	
I <sub>OZ(off)</sub>	output current	$V_O = 0$				-500	μΑ
I <sub>IH</sub>	High-level input current	V <sub>I</sub> = 5.5 V				10	μΑ
I <sub>IL</sub>	Low-level input current	V <sub>I</sub> = 0				-10	μΑ
			All outputs at high level			38	
I <sub>CC1</sub>	Output supply current	$I_{\Omega} = 0$	All outputs at low level			70	mA
·001	Calpat Supply Surroin	10 – 0	all outputs at high impedance			25	ША
			All outputs at high level			33	
laa.	Output supply current	I <sub>O</sub> = 0	All outputs at low level			20	nA
I <sub>CC2</sub>	Output supply current	10 - 0	All outputs at high impedance			5	

# 7.5 Switching Characteristics

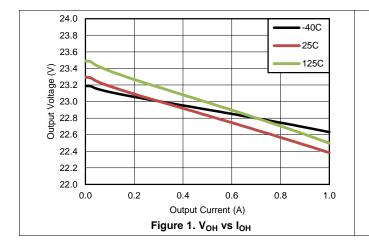
over operating free-air temperature range (unless otherwise noted),  $V_{CC1}$  = 5 V,  $V_{CC2}$  = 24 V,  $C_L$  = 30 pF,  $T_A$  = 25°C

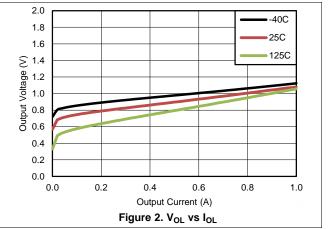
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>d1</sub>	Delay time, high-to-low-level output from A input		400			ns
t <sub>d2</sub>	Delay time, low-to-high-level output from A input	Soo Figure 2	800			ns
t <sub>TLH</sub>	Transition time, low-to-high-level output	See Figure 3	300			ns
t <sub>THL</sub>	Transition time, high-to-low-level output		300			ns
t <sub>en1</sub>	Enable time to the high level			700		ns
t <sub>en2</sub>	Enable time to the low level	Soo Figure 4	400			ns
t <sub>dis1</sub>	Disable time from the high level	See Figure 4 900		ns		
t <sub>dis2</sub>	Disable time from the low level			600		ns



# 7.6 Typical Characteristics

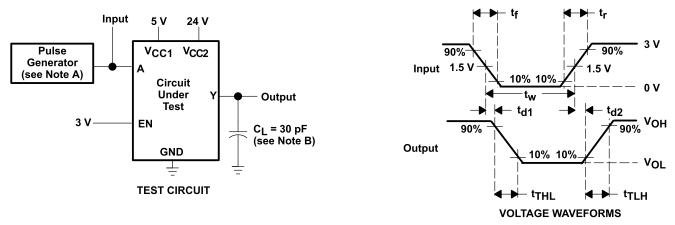
 $V_{CC1} = 5 \text{ V}, V_{CC2} = 24 \text{ V}$ 





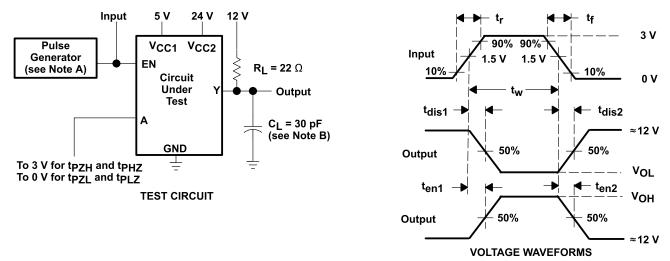


## 8 Parameter Measurement Information



- A. The pulse generator has the following characteristics:  $t_r \le 10$  ns,  $t_f \le 10$  ns,  $t_w = 10$   $\mu$ s,  $P_{RR} = 5$  kHz,  $Z_O = 50$   $\Omega$
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 3. Test Circuit and Switching Times from Data Inputs



- A. The pulse generator has the following characteristics:  $t_r \le 10$  ns,  $t_f \le 10$  ns,  $t_w = 10$   $\mu$ s,  $P_{RR} = 5$  kHz,  $Z_O = 50$   $\Omega$
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 4. Test Circuit and Switching Times from Enable Inputs



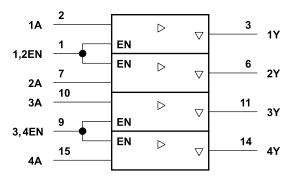
### 9 Detailed Description

#### 9.1 Overview

The SN754410 is a quadruple high-current half-H driver designed to provide bidirectional drive currents up to 1 A at voltages from 4.5 V to 36 V. The device is designed to drive inductive loads such as relays, solenoids, DC and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications. All inputs are compatible with TTL and low-level CMOS logic. Each output (Y) is a complete totem-pole driver with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs become active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in a high-impedance state. With the proper data inputs, each pair of drivers form a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

A separate supply voltage ( $V_{CC1}$ ) is provided for the logic input circuits to minimize device power dissipation. Supply voltage  $V_{CC2}$  is used for the output circuits. The SN754410 is designed for operation from  $-40^{\circ}$ C to 85°C.

#### 9.2 Functional Block Diagram



This symbol is in accordance with ANSI/IEEE Std 91-1984and IEC Publication 617-12.

#### 9.3 Feature Description

#### 9.3.1 High Current, High Voltage Outputs

Four high current and high voltage outputs feature clamp diodes for inductive load driving.

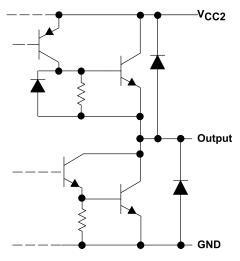


Figure 5. Typical of All Outputs



### **Feature Description (continued)**

### 9.3.2 TTL Compatible Inputs

Data inputs and enable inputs are compatible with TTL. 3.3-V CMOS logic is also acceptable, however open or high impedance input voltage can approach  $V_{CC1}$  voltage.

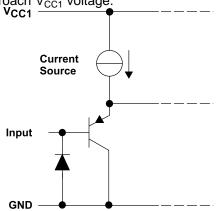


Figure 6. Equivalent of Each Input

#### 9.4 Device Functional Modes

Table 1. Function Table<sup>(1)</sup>

INPL	ITS <sup>(2)</sup>	OUTPUTS
Α	EN	Y
Н	Н	Н
L	Н	L
X	L	Z

(1) H = high-level

L = low-level

X = irrelevant

Z = high-impedance (off)

(2) In the thermal shutdown mode, the output is in a high-impedance state regardless of the input levels.



### 10 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

Provide a 5-V supply to V<sub>CC1</sub> and valid logic input levels to data and enable inputs. V<sub>CC2</sub> must be connected to a power supply capable of suppling the needed current and voltage demand for the loads connected to the

### 10.2 Typical Application

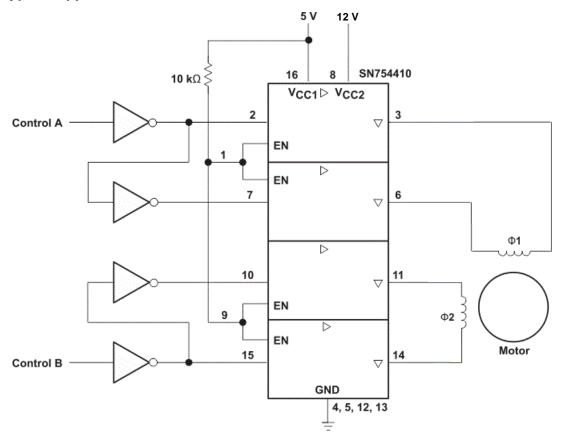


Figure 7. Typical Application Schematic

## 10.2.1 Design Requirements

The design techniques in the following sections may be used for applications which fall within the following requirements.

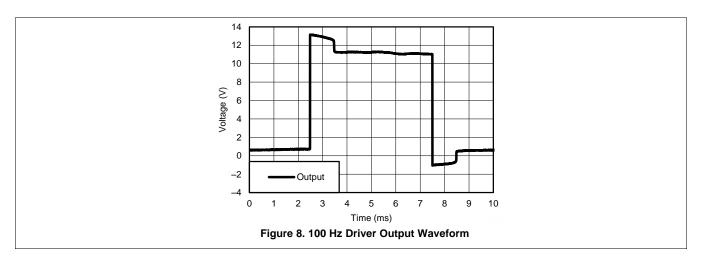
- 4.5-V minimum and 36-V maximum  $V_{\text{CC2}}$  voltage
- 1000-mA or less output current per channel
- 5-V supply with 10% tolerance or less
- TTL compatible logic inputs



# **Typical Application (continued)**

### 10.2.2 Application Curves

Driver output voltage waveform with a two phase stepper motor; 12-V  $20-\Omega$  coils.



# 11 Power Supply Recommendations

 $V_{CC1}$  is 5 V  $\pm$  0.5 V and  $V_{CC2}$  can be same supply as  $V_{CC1}$  or a higher voltage supply with peak voltage up to 36 V. Bypass capacitors of 0.1 uF or greater should be used at  $V_{CC1}$  and  $V_{CC2}$  pins. There are no power up or power down supply sequence order requirements.



### 12 Layout

### 12.1 Layout Guidelines

Place device near the load to keep output traces short to reduce EMI. Use solid vias to transfer heat from ground pins to circuit board's ground plane.

#### 12.2 Layout Example

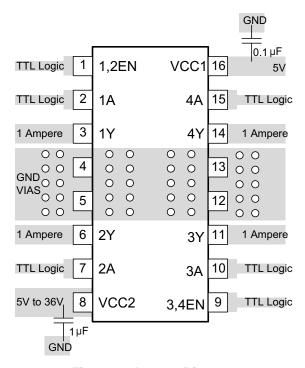


Figure 9. Layout Diagram

### 13 Device and Documentation Support

### 13.1 Trademarks

All trademarks are the property of their respective owners.

#### 13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN754410NE	Active	Production	PDIP (NE)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN754410NE
SN754410NE.A	Active	Production	PDIP (NE)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN754410NE
SN754410NEE4	Active	Production	PDIP (NE)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN754410NE

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



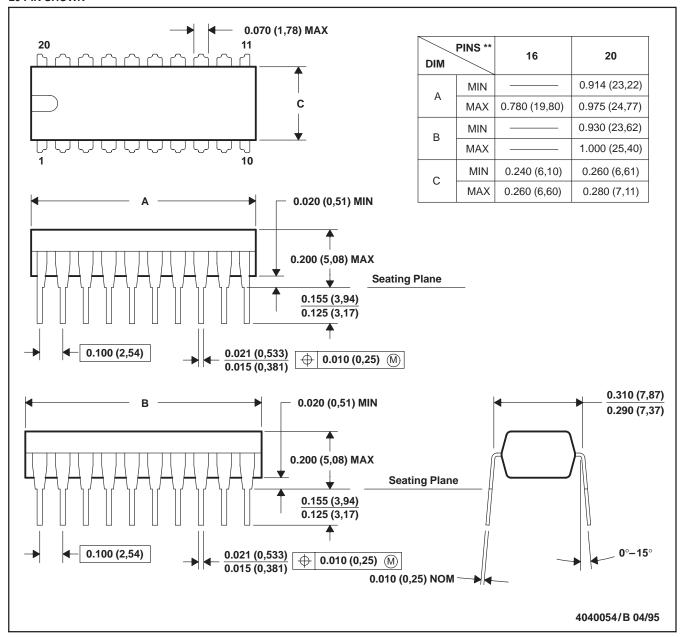
\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN754410NE	NE	PDIP	16	25	506	13.97	11230	4.32
SN754410NE.A	NE	PDIP	16	25	506	13.97	11230	4.32
SN754410NEE4	NE	PDIP	16	25	506	13.97	11230	4.32

### NE (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

#### 20 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001 (16 pin only)

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